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SECRET

UNITED STATES GOVERNMENT

# Memorandum

TO : C/GSD

DATE: 24 March 1965

FROM : DAD/S&D

SUBJECT:

25X1D

1. In the final report of the [REDACTED] Second Model, I note that reference is made to the use of copper-plated stainless steel wire for integrated circuit board interconnections. Soldering problems occurred whenever the copper plating was removed from the stainless steel, of course. They recommend the use of a phosphor bronze wire in the future.

2. I am concerned that during exposure to salt air atmosphere, etc., that corrosion may take place due to the dissimilar metal problem and I don't exactly understand the use of stainless steel wire in the first place. Are the units sealed so that this problem would be precluded?